

**AMENDED VERSION OF SECTION OF SPECIFICATION**

Applicants respectfully request the substitution of the table below for the table appearing at the top of page 11 of the description of this application as filed.

Application Number	Title of Application	First Named Inventor
09/687,485	Semiconductor Package Having Increased Solder Joint Strength	Kil Chin Lee
09/687,487	Clamp and Heat Block Assembly For Wire Bonding a Semiconductor Package Assembly	Young Suk Chung
09/687,876	Near Chip Size Semiconductor Package	Sean Timothy Crowley
09/687,531	Stackable Semiconductor Package and Method for Manufacturing Same	Sean Timothy Crowley
09/687,530	Stackable Semiconductor Package and Method for Manufacturing Same	Jun Young Yang
09/687,126	Method of and Apparatus for Manufacturing Semiconductor Packages	Hyung Ju Lee
09/687,493	Semiconductor Package Having Improved Adhesiveness and Ground Bonding	Sung Sik Jang
09/687,541	Semiconductor Package Leadframe Assembly and Method of Manufacture	Young Suk Chung

Replacement sheet 11 of the specification is enclosed for the convenience of the Examiner in entering the preceding amendment.